Product / Package Information

Package	SOT143
Body Size	
Lead Count	4
Terminal Finish	100 Sn

Environmental Compliance Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	5.00 E-03	83.25	832500	48.52	485168
Thermosets	Epoxy resin	Proprietary	3.25 E-04	5.42	54200	3.16	31587
Thermosets	Phenol resin	Proprietary	2.07 E-04	3.45	34500	2.01	20106
Other inorganic materials	Metal Hydroxide	Proprietary	3.25 E-04	5.42	54200	3.16	31587
Others	Others	Proprietary	1.48 E-04	2.46	24600	1.43	14336
Subtotal			6.00 E-03	100.0	1000000	58.28	582784

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Iron & its alloys	Iron	7439-89-6	1.82 E-03	56.70	567000	17.72	177198
Iron & its alloys	Nickel	7440-02-0	1.34 E-03	41.50	415000	12.97	129695
Iron & its alloys	Manganese	7439-96-5	2.57 E-05	0.80	8000	0.25	2500
Iron & its alloys	Cobalt	7440-48-4	1.61 E-05	0.50	5000	0.16	1563
Iron & its alloys	Silicon	7440-21-3	9.65 E-06	0.30	3000	0.09	938
Iron & its alloys	Chromium	7440-47-3	3.22 E-06	0.10	1000	0.03	313
Iron & its alloys	Aluminum	7429-90-5	3.22 E-06	0.10	1000	0.03	313
Subtotal			3.22 E-03	100.00	1000000	31.25	312518

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.25 E-05	100.0	1000000	0.32	3157

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	3.85 E-04	100.0	1000000	3.74	37435

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.00 E-04	99.99	1000000	0.97	9713

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	5.00 E-04	100.0	1000000	4.86	48565

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silicon Dioxide	Proprietary	2.76 E-05	46.00	460000	0.27	2681
Thermoset	Epoxy Resin	Proprietary	2.76 E-05	46.00	460000	0.27	2681
Others	Curing agent & hardener	Proprietary	4.80 E-06	8.00	80000	0.05	466
Subtotal			6.00 E-05	100	1000000	0.58	5828

	Weight (g)	Percentage (%)	PPM
Package Totals	**1.03 E-02**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability
any inaccuracy of such information.

ANALOG DEVICES

Product / Package Information

Package	SOT143
Body Size	
Lead Count	3
Terminal Finish	85Sn15Pb

Environmental Compliance Information

RoHS Compliant	No
High Temperature Compliant	No
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	5.00 E-03	83.25	832500	48.26	482609
Thermosets	Epoxy resin	Proprietary	3.25 E-04	5.42	54200	3.14	31420
Thermosets	Phenol resin	Proprietary	2.07 E-04	3.45	34500	2.00	20000
Other inorganic materials	Metal Hydroxide	Proprietary	3.25 E-04	5.42	54200	3.14	31420
Others	Others	Proprietary	1.48 E-04	2.46	24600	1.43	14261
Subtotal			6.00 E-03	100.0	1000000	57.97	579710

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Iron & its alloys	Iron	7439-89-6	1.82 E-03	56.70	567000	17.63	176263
Iron & its alloys	Nickel	7440-02-0	1.34 E-03	41.50	415000	12.90	129011
Iron & its alloys	Manganese	7439-96-5	2.57 E-05	0.80	8000	0.25	2487
Iron & its alloys	Cobalt	7440-48-4	1.61 E-05	0.50	5000	0.16	1554
Iron & its alloys	Silicon	7440-21-3	9.65 E-06	0.30	3000	0.09	933
Iron & its alloys	Chromium	7440-47-3	3.22 E-06	0.10	1000	0.03	311
Iron & its alloys	Aluminum	7429-90-5	3.22 E-06	0.10	1000	0.03	311
Subtotal			3.22 E-03	100.00	1000000	31.09	310870

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.25 E-05	100.0	1000000	0.31	3140

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	3.74 E-04	85.0	850000	3.61	36135
Tin & its alloys	Lead	7439-92-1	6.60 E-05	15.0	150000	0.64	6377
Subtotal			4.40 E-04	100.0	1000000	4.25	42512

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.00 E-04	99.99	1000000	0.97	9662

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	5.00 E-04	100.0	1000000	4.83	48309

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silicon Dioxide	14808-60-7	2.99 E-05	49.90	499000	0.29	2893
Organic materials	Reaction product: bisphenol-F-(epichlorhydrin); epoxy resin (number average molecular weight <= 700)	9003-36-5	1.20 E-05	20.00	200000	0.12	1159
Organic materials	1,4-bis(2,3-epoxypropoxy)butane	2425-79-8	1.20 E-05	20.00	200000	0.12	1159
Others	Aromatic Amine	Proprietary	3.00 E-06	5.00	50000	0.03	290
Glass	Glass	65997-17-3	3.00 E-06	5.00	50000	0.03	290
Organic materials	Reaction product: bisphenol-A-(epichlorhydrin); epoxy resin (number average molecular weight <= 700)	25068-38-6	6.00 E-08	0.10	1000	0.00	6
Subtotal			6.00 E-05	100.00	1000000	0.58	5797

	Weight (g)	Percentage (%)	PPM
Package Totals	**1.04 E-02**	**100.00**	**1000000**

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any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary